













ESD

TVS

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GDT

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SMCJ5.0(C)A -SMCJ440(C)A

Product specification





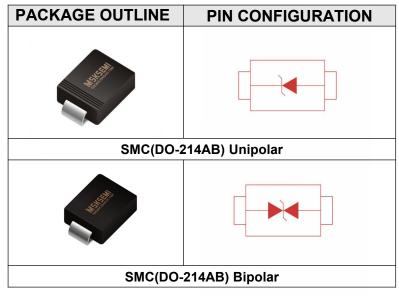
Features

• 1500W peak pulse power capability at 10/

1000µs waveform

- For surface mounted applications to optimize board space
- Glass passivated chip junction
- Halogen free and RoHS compliant

Reference News



Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation on 10/1000 us waveform	Р _{РРМ}	1500	W
Peak Forward Surge Current,8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM} (UNI)	200	А
Power dissipation on Infinite heat sink at TA=50°C	PD	6.5	W
Maximum instantaneous forward voltage at 100 A for unidirectional only	VF	3.5	V
Peak Pulse Current on 10/1000 us waveform	PPM	See Next Table	А
Typical Thermal Resistance Junction to Ambient(Note 1)	R _{θJA} R _{θJL}	75 15	°C/W
Operating Junction Temperature and Storage Temperature Range	Tj, Tstg	-55 ~ +150	°C

NOTES:

1. Mounted on 8 mm^2 (0.13mm thick) land areas.

MECHANICAL DATA

- Case: SMC
- Terminals: Solderable per MIL-STD-750 , Method 2026
- Approx. Weight: 0.22g (0.0077oz)



Characteristics at Ta = 25° C

Туре				Reverse Stand-off Voltage	Breakdown Voltage		Test Current	Max Clamping Voltage	Peak Pulse Current	Maximum Reverse Leakage
		Marking		Vrmw	V _{br} @ I _t		ե	Vc @ IPP	Ірр	I _R
UNI	BI	UNI	BI	V	Min(V)	Max(V)	mA	V	Α	μA
SMCJ5.0A	SMCJ5.0CA	GDE	BDE	5	6.4	7	10	9.2	163	800
SMCJ6.0A	SMCJ6.0CA	GDG	BDG	6	6.67	7.37	10	10.3	145.7	800
SMCJ6.5A	SMCJ6.5CA	GDK	BDK	6.5	7 .22	7 .98	10	11.2	134	500
SMCJ7.0A	SMCJ7.0CA	GDM	BDM	7	7 .78	8.6	10	12	125	200
SMCJ7 .5A	SMCJ7.5CA	GDP	BDP	7.5	8.33	9.21	1	12.9	116.3	100
SMCJ8.0A	SMCJ8.0CA	GDR	BDR	8	8.89	9.83	1	13.6	110.3	50
SMCJ8.5A	SMCJ8.5CA	GDT	BDT	8.5	9.44	10.4	1	14.4	104 .2	20
SMCJ9.0A	SMCJ9.0CA	GDV	BDV	9	10	11.1	1	15.4	97.4	10
SMCJ10A	SMCJ10CA	GDX	BDX	10	11.1	12.3	1	17	88.3	5
SMCJ11A	SMCJ11CA	GDZ	BDZ	11	12.2	13.5	1	18.2	82.5	1
SMCJ12A	SMCJ12CA	GEE	BEE	12	13.3	14 .7	1	19.9	75.4	1
SMCJ13A	SMCJ13CA	GEG	BEG	13	14 .4	15.9	1	21.5	69.8	1
SMCJ14A	SMCJ14CA	GEK	BEK	14	15.6	17 .2	1	23.2	64 .7	1
SMCJ15A	SMCJ15CA	GEM	BEM	15	16.7	18.5	1	24.4	61.5	1
SMCJ16A	SMCJ16CA	GEP	BEP	16	17 .8	19.7	1	26	57.7	1
SMCJ17A	SMCJ17CA	GER	BER	17	18.9	20.9	1	27.6	54.4	1
SMCJ18A	SMCJ18CA	GET	BET	18	20	22.1	1	29.2	51.4	1
SMCJ20A	SMCJ20CA	GEV	BEV	20	22.2	24 .5	1	32.4	46.3	1
SMCJ22A	SMCJ22CA	GEX	BEX	22	24.4	26.9	1	35.5	42.3	1
SMCJ24A	SMCJ24CA	GEZ	BEZ	24	26.7	29 .5	1	38.9	38.6	1
SMCJ26A	SMCJ26CA	GFE	BFE	26	28.9	31.9	1	42.1	35.7	1
SMCJ28A	SMCJ28CA	GFG	BFG	28	31.1	34.4	1	45.4	33.1	1
SMCJ30A	SMCJ30CA	GFK	BFK	30	33.3	36.8	1	48.4	31	1
SMCJ33A	SMCJ33CA	GFM	BFM	33	36.7	40.6	1	53.3	28.2	1
SMCJ36A	SMCJ36CA	GFP	BFP	36	40	44 .2	1	58.1	25 .9	1
SMCJ40A	SMCJ40CA	GFR	BFR	40	44.4	49.1	1	64.5	23.3	1
SMCJ43A	SMCJ43CA	GFT	BFT	43	47 .8	52.8	1	69.4	21.7	1
SMCJ45A	SMCJ45CA	GFV	BFV	45	50	55.3	1	72.7	20.6	1
SMCJ48A	SMCJ48CA	GFX	BFX	48	53.3	58.9	1	77 .4	19.4	1
SMCJ51A	SMCJ51CA	GFZ	BFZ	51	56.7	62.7	1	82.4	18.2	1
SMCJ54A	SMCJ54CA	GGE	BGE	54	60	66.3	1	87.1	17 .3	1
SMCJ58A	SMCJ58CA	GGG	BGG	58	64.4	71.2	1	93.6	16.1	1
SMCJ60A	SMCJ60CA	GGK	BGK	60	66.7	73.7	1	96.8	15.5	1
SMCJ64A	SMCJ64CA	GGM	BGM	64	71.1	78.6	1	103	14 .6	1
SMCJ70A	SMCJ70CA	GGP	BGP	70	77 .8	86	1	113	13.3	1
SMCJ75A	SMCJ75CA	GGR	BGR	75	83.3	92.1	1	121	12.4	1
SMCJ78A	SMCJ78CA	GGT	BGT	78	86.7	95.8	1	126	11.9	1
SMCJ85A	SMCJ85CA	GGV	BGV	85	94.4	104	1	137	11	1
SMCJ90A	SMCJ90CA	GGX	BGX	90	100	111	1	146	10.3	1
SMCJ100A	SMCJ100CA	GGZ	BGZ	100	111	123	1	162	9.3	1
SMCJ110A	SMCJ110CA	GHE	BHE	110	122	135	1	177	8.5	1
SMCJ120A	SMCJ120CA	GHG	BHG	120	133	147	1	193	7.8	1
SMCJ130A	SMCJ130CA	GHK	BHK	130	144	159	1	209	7.2	1
SMCJ150A	SMCJ150CA	GHM	BHM	150	167	185	1	243	6.2	1
SMCJ160A	SMCJ160CA	GHP	BHP	160	178	197	1	259	5.8	1

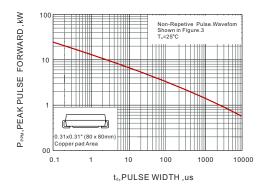


SMCJ5.0(C)A -SMCJ440(C)A

ту	/рө	Marking		Reverse Stand-off Voltage	Volt	kdown kage	Test Current	Max Clamping Voltage	Peak Pulse Current	Maximum Reverse Leakage
				Vrmw	VBR	@ I _T	ե	Vc @ I _{PP}	IPP	l _R
UNI	BI	UNI	BI	V	Min(V)	Max(V)	mA	V	Α	μA
SMCJ170A	SMCJ170CA	GHR	BHR	170	189	209	1	275	5.5	1
SMCJ180A	SMCJ180CA	GHT	BHT	180	201	222	1	292	5.1	1
SMCJ200A	SMCJ200CA	GHV	BHV	200	224	247	1	324	4.6	1
SMCJ220A	SMCJ220CA	GHX	BHX	220	246	272	1	356	4.2	1
SMCJ250A	SMCJ250CA	GHZ	BHZ	250	279	309	1	405	3.7	1
SMCJ300A	SMCJ300CA	GJE	BJE	300	335	371	1	486	3.1	1
SMCJ350A	SMCJ350CA	GJG	BJG	350	391	432	1	567	2.6	1
SMCJ400A	SMCJ400CA	GJK	BJK	400	447	494	1	648	2.3	1
SMCJ440A	SMCJ440CA	GJM	BJM	440	492	543	1	713	2.1	1



Fig.1 Peak Pulse Power Rating Curve



150 T_A=25° Pulse V as the P Current dth (td) is Defined it where the Peak. tr=10us Ippm, Peak Pulse Current (%) 100 Peak Value 80 Half Value-Ipp/2 60 10/1 40 20 0 0 1.0 2.0 3.0 4.0 T,TIME,ms

Fig.2 Pulse Waveform

Fig.4 Typical Junction Capacitance

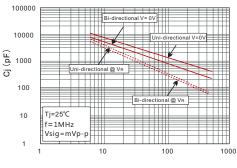
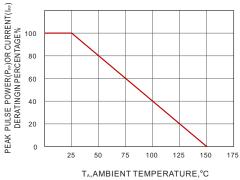
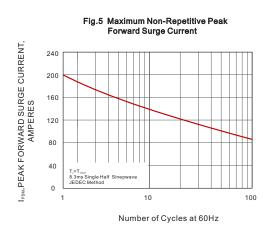


Fig.3 Forward Current Derating Curve

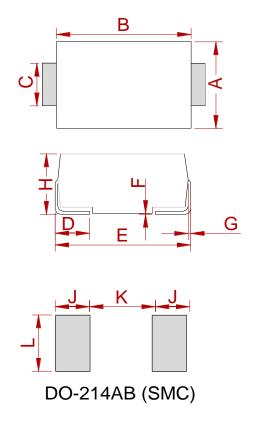




V_{BR} - Reverse Breakdown Voltage (V)



PACKAGE MECHANICAL DATA



	Dimensions							
Ref.	Millir	neters	Inches					
	Min.	Max.	Min.	Max.				
А	5.75	6.25	0.226	0.246				
В	6.90	7.40	0.272	0.291				
С	2.75	3.25	0.108	0.128				
D	0.95	1.52	0.037	0.060				
E	7.70	8.20	0.303	0.323				
F	0.051	0.203	0.002	0.008				
G	0.15	0.31	0.006	0.012				
Н	2.15	2.62	0.085	0.103				
J	2.40		0.094					
К		4.20		0.165				
L	3.30		0.130					

REELSPECIFICATION

P/N	PKG	QTY
SMCJ5.0(C)A -SMCJ440(C)A	SMC	3000



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